# Direct Visualization of the Impacts of EUV Mask Roughness

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## Band-limited imaging and propagation transforms phase roughness to intensity speckle



In focus  $\sigma = 0.5$ 



Contrast = 0.9%



## Band-limited imaging and propagation transforms phase roughness to intensity speckle



50-nm defocus  $\sigma = 0.5$ 



Contrast = 6%



## Multilayer speckle directly observed with EUV microscope



Images from SEMATECH Berkeley AIT, courtesy of Ken Goldberg, LBNL





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# Focus plays dominant role in roughness induced LWR



75-pm roughness, 0.33 NA, 0.7 Sigma, 22-nm HP

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## Measuring multilayer roughness

## AFM blind to true EUV roughness







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## AFM blind to true EUV roughness



S. George et al., Proc. SPIE **7969**, 79690E (2011)

## Scatterometry measures true EUV roughness



## Demonstration 1: Measure multilayer speckle with SHARP

Source: Synchrotron

**Optics:** Mirrors & Zoneplate-lenses

**4×NA:** 0.25–0.625

**σ**: Programmable

Nav: Full-mask xy

Speed: ~8 series/hr







## Good fit between SHARP and modeling





Demonstration 2: Measure multilayerinduced LWR with Samsung SERM tool

## <u>Scanning EUV Reticle Microscope</u>

### **Outline of the tool development**

- The zone plate optics was designed and fabricated by LBNL.
- The high harmonic source was developed by Samsung and FST using COHERENT Ti:Sapphire femtosecond laser(λ = 800nm, pulse width= 46fs) and the whole system was integrated by Samsung.











# Correlation method used to extract mask roughness in presence of noise



**Total Mask**induced LWR 1.60 nm Pattern LWR 1.48 nm Multilayer LWR 0.62 nm Simulated Multlayer LWR 0.60 nm

 $LWR_{msk} = R \times LWR_{meas}^*$ 

\* Appl. Opt. 48, 3302-3307 (2009)



# Impact on inspection

#### Patterned mask inspection

		CDU Requirement				~•••••••••••••••••••••••••••••••••••••				
RSR (pm)	Speckle LWR (nm)	10%		20%				oqui		
20	0.16	2.81E-08		4.00E-63						
30	0.24	2.77E-04		2.65E-47	,					
44	0.35	7.39E+00		7.93E-30		Brightfield blank				
56	0.45	4.37E+03		6.15E-19		inspection				
69	0.55	3.40E		Printable defect height (nm)						
81	0.65	6.89E	RSR (pm)	0.3	0.4	0.5	0.6			
94	0.75	5.83E	50	6.59E-05	3.44E-17	6.40E-33	4.16E-52			
106	0.85	2.77E <sup>.</sup>	55	3.74E-02	2.52E-12	2.42E-25	3.26E-41			
119	0.95	8.90E	60	4.71E+00	1.28E-08	1.43E-19	6.40E-33	_	Darkfield	
			65	2.05E+02	9.92E-06	4.47E-15	1.84E-26		blook	
			70	4.15E+03	1.96E-03	1.67E-11	2.48E-21	_	DIANK	
			80	3.48E+05	4.71E+00	2.96E-06 8.51E-14		ins	inspection	
			90	7.44E+06			Target defec	t height (nm)	eight (nm)	
			100	6.//E+0/	RSR (pm)	0.4	0.6	0.8	1.0	
			110	3.52E+08	50	5.28E+06	8.00E-08	2.22E-44	3.90E-121	
			120	2 27F±09	60	3.79E+08	5.72E+01	1.01E-16	7.75E-54	
			150	3.372105	70	2.63E+09	4.10E+05	8.39E-05	6.37E-25	
					80	7.24E+09	3.37E+07	5.72E+01	7.71E-11	
					90	1.30E+10	3.79E+08	7.92E+04	2.64E-03	
					100	1.88E+10	1.59E+09	5.28E+06	5.72E+01	
					110	2.40E+10	3.95E+09	7.04E+07	2.54E+04	
					120	2.84E+10	7.24E+09	3.79E+08	1.26E+06	

## Summary

- Roughness has significant impact on inspection
- Actinic characterization likely required
- Model verified using two different actinic microscopes
- System modeling points to EUV roughness requirements close to 50 pm





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